

20V PNP SILICON LOW SATURATION TRANSISTOR IN SOT23

Features and Benefits

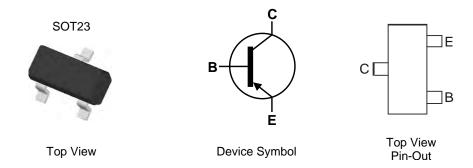
- BV_{CEO} > -20V
- I_C = -1.5A Continuous Collector Current
- I_{CM} = -6A Peak Pulse Current
- Low Saturation Voltage V_{CE(sat)} < -200mV @ -1A
- $R_{SAT} = 97m\Omega$ for a low equivalent on-resistance
- hFE characterised up to -6A for high current gain hold-up
- 625mW power dissipation due to SuperSOT package
- Complementary part number FMMT618
- Lead Free, RoHS Compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT-23
- UL Flammability Rating 94V-0
- Case material: molded Plastic.
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Matte Tin Finish annealed over Copper plated Alloy
 42 leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (Approximate)

Applications

- MOSFET Gate Driving
- DC-DC Converters
- Charging circuit
- Power switches

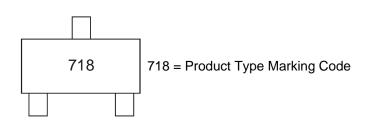


Ordering Information

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FMMT718TA	718	7	8	3,000
FMMT718TC	718	13	8	10,000

Note: 1. No purposefully added lead.

Marking Information







Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-20	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Base Voltage	V _{EBO}	-5	V
Continuous Collector Current	Ic	-1.5	Α
Peak Pulse Current	I _{CM}	-6	Α
Base Current	I _B	-500	mA

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 2)	Pn	625	mW
Linear Rating Factor	(/		5	mW/°C
Thermal Resistance, Junction to Ambient (Note 2)		$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Lead	(Note 3)	$R_{ heta JL}$	194	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C	

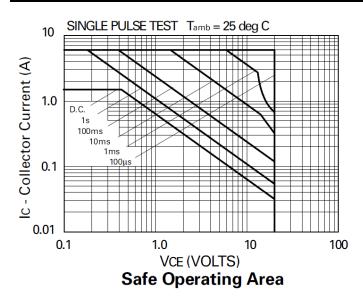
Notes:

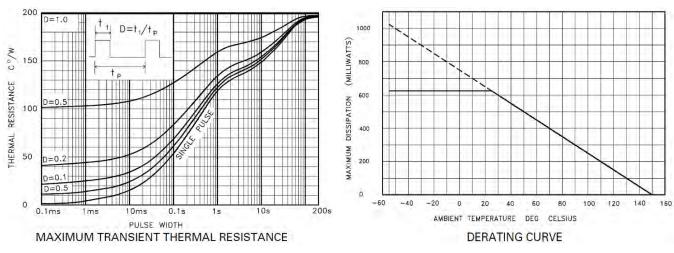
^{2.} For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

^{3.} Thermal resistance from junction to solder-point (at the end of the collector lead).



Thermal Characteristics and Derating information





Device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.





Electrical Characteristics @T_A = 25°C unless otherwise specified

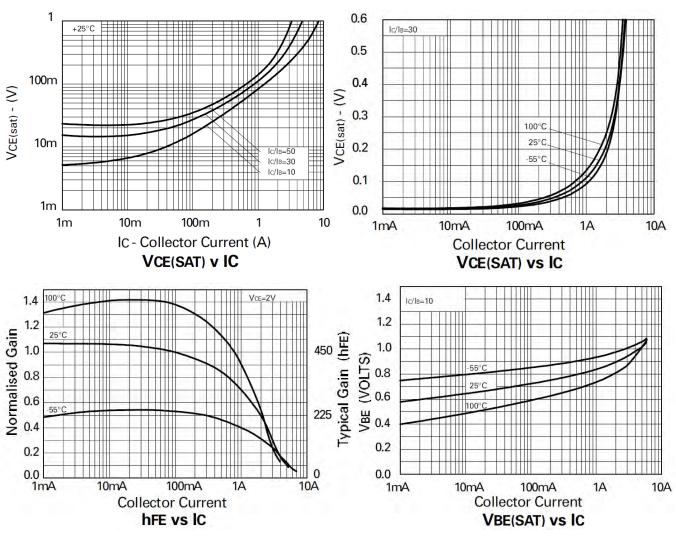
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-20	-65		V	$I_C = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 4)	BV _{CEO}	-20	-55		V	$I_C = -10 \text{ mA}$
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	-8.8		V	$I_E = -100 \mu A$
Collector Cutoff Current	I _{CBO}			-100	nA	V _{CB} = -15V
Emitter Cutoff Current	I _{EBO}			-100	nA	$V_{EB} = -4V$
Collector Emitter Cutoff Current	I _{CES}			-100	nA	V _{CE} = -15V
Static Forward Current Transfer Ratio (Note 4)	h _{FE}	300 300 150 35 15	475 450 230 70 30			$\begin{split} I_{C} &= -10 \text{mA}, \ V_{CE} = -2 \text{V} \\ I_{C} &= -100 \text{mA}, \ V_{CE} = -2 \text{V} \\ I_{C} &= -2 \text{A}, \ V_{CE} = -2 \text{V} \\ I_{C} &= -4 \text{A}, \ V_{CE} = -2 \text{V} \\ I_{C} &= -6 \text{A}, \ V_{CE} = -2 \text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 4)	V _{CE(sat)}		-16 -130 -145	-40 -200 -220	mV mV mV	$I_C = -0.1A$, $I_B = -10mA$ $I_C = -1A$, $I_B = -20mA$ $I_C = -1.5A$, $I_B = -50mA$
Base-Emitter Turn-On Voltage(Note 4)	V _{BE(on)}		-0.81	-1.0	V	I _C = -2A, V _{CE} = -2V
Base-Emitter Saturation Voltage(Note 4)	V _{BE(sat)}		-0.87	-1.0	V	I _C = -1.5A, I _B = -50mA
Output Capacitance	C _{obo}		34	43	pF	$V_{CB} = -10V$, $f = 1MHz$
Transition Frequency	f⊤	150	180		MHz	$V_{CE} = -10V, I_{C} = -50mA,$ f = 100MHz
Turn-On Time	t _{on}		68		ns	V _{CC} =-10V, I _C =-1A
Turn-Off Time	t _{off}		270		ns	$I_{B1} = I_{B2} = -20\text{mA}$

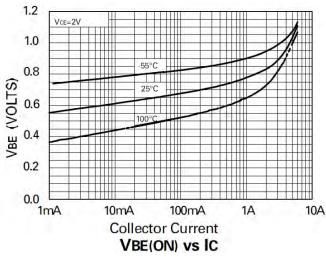
Note:

4. Measured under pulsed conditions. Pulse width \leq 300 $\mu s.$ Duty cycle \leq 2%



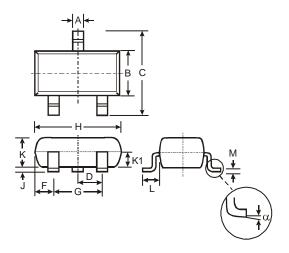
Typical Electrical Characteristics





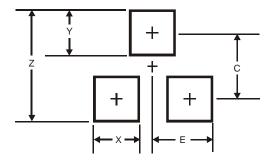


Package Outline Dimensions



	SOT23					
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.903	1.10	1.00			
K 1	-	1	0.400			
L	0.45	0.61	0.55			
M	0.085	0.18	0.11			
α	0°	8°	-			
All	All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
Е	1.35





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